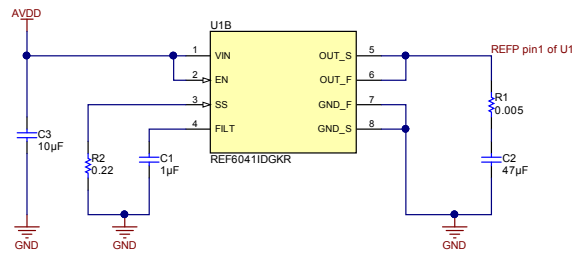


Alternate Reference Circuit Schematic REF6041



Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 2/11/2017
TID: TIDU504	Project Title: TIPD173	
Number: [blank]	Rev: B	Sheet Title: Alternate Reference Circuit
Version control disabled	Assembly Variant: No Variations	Sheet: 2 of 3
Drawn By: Cynthia Sosa	File: TIPD_112_reamp_BlankSheet_SchDoc	Size: B
Engineer: Jason Wu	Contact: http://www.ti.com/support	http://www.ti.com



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